IEEE COMPUTER SOCIETY ANNUAL SYMPOSIUM ON VLSI

CALL FOR PAPERS

www.isvlsi2018.org

July 9-11, 2018 Hong Kong, China



quality will continue at this and future editions of the Symposium.

and thermal analysis, statistical approaches.

memories, FPGA designs, FPGA based systems.

Contributions are sought in the following areas



The Symposium explores emerging trends and novel ideas and concepts covering a broad range of

topics in the area of VLSI: from VLSI circuits, systems and design methods, to system level design

and system-on-chip issues, to bringing VLSI methods to new areas and technologies like nano- and molecular devices, hardware security, etc. Future design methodologies are also one of the key

topics at the Symposium, as well as new EDA tools to support them. Over three decades the

Symposium has been a unique forum promoting multidisciplinary research and new visionary

approaches in the area of VLSI, bringing together leading scientists and researchers from academia and industry. The conference proceedings will be indexed in the IEEE Xplore Digital Library.

Selected high quality papers from ISVLSI 2018 will be further considered for two Journal Special

Issues: 1) IEEE Transactions on Nanotechnology (impact factor 2.485), and 2) IEEE Consumer

Electronics Magazine (impact factor 1.153). The Symposium has established a reputation in

bringing together well-known international scientists as invited speakers; the emphasis on high

1) Analog and Mixed-Signal Circuits (AMS): Analog/mixed-signal circuits, RF and communication

2) Computer-Aided Design and Verification (CAD): Hardware/software co-design, logic and

3) Digital Circuits and FPGA based Designs (DCF): Digital circuits, chaos/neural/fuzzy-logic

4) Emerging and Post-CMOS Technologies (EPT): Nanotechnology, molecular electronics, quantum

5) System Design and Security (SDS): Structured and Custom Design methodologies,

microprocessors/micro-architectures for performance and low power, embedded processors,

analog/digital/mixed-signal systems, NoC, power and temperature aware designs, Hardware

security, Cryptography, watermarking, and IP protection, TRNG and security oriented circuits,

6) Testing, Reliability, and Fault-Tolerance (TRF): Analog/digital/mixed-signal testing, design for

The Symposium Program will include contributed papers and speakers invited by the Program

Committee as well as a poster session. The keynotes, special sessions and Student Research Forum

are planned as well. Authors are invited to submit full-length, original, unpublished papers. To

enable blind review, the author list should be omitted from the main document. Initial submissions

testability and reliability, online testing techniques, static and dynamic defect- and fault-

RTD, QCA, reversible logic, and CAD tools for emerging technology devices and circuits.

devices, optical computing, spin-based computing, biologically-inspired computing, CNT, SET,

circuits, high speed/low-power circuits, energy efficient circuits, near and sub-threshold circuits,

behavioral synthesis, simulation and formal verification, physical design, signal integrity, power

circuits, adaptive circuits, interconnects, VLSI aspects of sensor and sensor network.











General Chairs

- Wei Zhang
- Hong Kong Univ. of Sci. and Tech., China
- City University of Hong Kong, China
- Hong Kong Polytechnic University

TPC Chairs

- Hai Li.
- Duke University, USA
- Yu Wang, Tsinghua University, China
- Wujie Wen,
- Florida International Univ., USA

Special Session Chairs

- Bei Yu,
- The Chinese Univ. of Hong Kong, China
- Yuan-Hao Chang,
- Academia Sinica, Taiwan

Web Chair

■ Theocharis Theocharides, University of Cyprus, Cyprus

Student Research Forum Chairs

- Anupam Chattopadhyay.
- Nanyang Technological Univ., Singapore
- Zheng Wang.

Shenzhen Institutes of Advanced Technology of the Chinese Academy of Science

Publication Chairs

- Colorado State University, USA
- Chenchen Liu,
- Clarkson University, USA

Publicity Chairs

- Guangyu Sun,
- Peking University, China
- Muhammad Shafique,
- Vienna University of Technology, Austria
- Jingtong Hu,
- University of Pittsburgh, USA
- Masaaki Kondo. The University of Tokyo, Japan
- Chun-Yi Lee,
- National Tsinghua University, Taiwan ■ Dhruva Ghai.
- Oriental University, India

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- Hong Kong Polytechnic Univ., Hong Kong
- Ray Chak-Chung Cheung,
- City Univ. of Hong Kong, Hong Kong

Industrial Liaison Chairs

- Wei Zhang,
- Hong Kong Univ. of Sci. and Tech., China
- Jürgen Becker.
- Karlsruhe Institute of Tech., Germany
- Zhihong Wu.
- Tongji University, China

Paper Submission Deadlines

recoverability, and variation aware design.

PUF circuits.

Paper Submission Deadline: March 4, 2018 Acceptance Notification: April 20, 2018 Submission of Final Version: May 10, 2018 Special Session Proposal Deadline: March 11, 2018

to the conference are limited to six pages in PDF format.











